



Material Content Data Sheet



Sales Product Name		TLE4678EL		Issued		22. January 2018			
MA#		MA001154562							
Package		PG-SSOP-14-2		Weight*		83.60 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.312	3.96	3.96	39621	39621	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103		
		non noble metal	zinc	7440-66-6	0.034	0.04		412	
		non noble metal	iron	7439-89-6	0.689	0.82		8242	
wire	noble metal	non noble metal	copper	7440-50-8	27.978	33.47	34.34	334669	343426
		noble metal	gold	7440-57-5	0.195	0.23	0.23	2337	2337
		organic material	carbon black	1333-86-4	0.096	0.11		1149	
encapsulation	plastics	epoxy resin	-	4.420	5.29		52874		
		inorganic material	silicondioxide	60676-86-0	43.530	52.07	57.47	520699	574722
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11676	11676	
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9182	9182	
glue	plastics	epoxy resin	-	0.398	0.48		4759		
		noble metal	silver	7440-22-4	1.194	1.43	1.91	14277	19036
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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